

IAR IDE User Manual Rev. 1.2

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1 Introduction

This manual is written to clarify some aspects that have to be taken into consideration when working with CC2430, CC2510 or CC1110 together with the IAR Workbench.

The CC2431 is in most of the aspects described in this manual equal to CC2430, and will not be mentioned explicit. CC2431 is only delivered with a flash size of 128 kB. Every configuration file available for CC2430 is also available for CC2431.

2 Definitions

CC2430-F32	CC2430 with 32KB FLASH
CC2430-F64	CC2430 with 64KB FLASH
CC2430-F128	CC2430 with 128KB FLASH
CCxx10	Refers to either CC2510 or the CC1110.

3 Installation

Install the IAR Embedded Workbench as described in the IAR User Manual.

3.1 Chipcon CC1110/ CC2510 Extensions

3.1.1 Configuration Files

CC2510/CC1110 has 4 configuration files associated. For CC2510 these files are installed with IAR Workbench, for CC1110 they can be downloaded from our web site. The configuration files should be located according to Table 2.

File name	Location	Description
CCxx10.i51	C:\Program Files\IAR Systems\Embedded Workbench 4.05\8051\config\derivatives\chipcon	Setup some parts of an IAR Project.
CCxx10.ddf	C:\Program Files\IAR Systems\Embedded Workbench 4.05\8051\config\derivatives\chipcon	Describe each register used in the debugger.
lnk51ew_ccxx10.xcl	C:\Program Files\IAR Systems\Embedded Workbench 4.05\8051\config	Set up the linker to reflect CCxx10.
ioCCxx10.h	C:\Program Files\IAR Systems\Embedded Workbench 4.05\8051\inc	Header file for CCxx10.

Table 1: Configuration files

3.1.2 Chipcon Library Files

The files which are described here are part of the Chipcon library and can be downloaded from www.chipcon.com.

In the IAR standard library, cexit will by default occupy one of the four hardware breakpoints. To free this breakpoint include the file below in the project.

- Chipcon_cexit.s51

Note:

Add \$TOOLKIT_DIR\$\SRC\LIB\ to Options -> Assembler -> Additional include directives.

3.2 Chipcon CC2430 Extensions

3.2.1 Configuration Files

CC2430 has five configuration files associated. These files are installed with IAR Workbench. The configuration files are located according to Table 2.

File name	Location	Description
CC2430.i51	C:\Program Files\IAR Systems\Embedded Workbench 4.05\8051\config\derivatives\chipcon	Setup some parts of an IAR Project.
CC2430.ddf	C:\Program Files\IAR Systems\Embedded Workbench 4.05\8051\config\derivatives\chipcon	Describe each register used in the debugger.
lnk51ew_cc2430.xcl	C:\Program Files\IAR Systems\Embedded Workbench 4.05\8051\config	Set up the linker to reflect CC2430.
lnk51ew_cc2430b.xcl	C:\Program Files\IAR Systems\Embedded Workbench 4.05\8051\config	Set up the linker to reflect CC2430 with banked code model.
ioCC2430.h	C:\Program Files\IAR Systems\Embedded Workbench 4.05\8051\inc	Header file for CC2430.

Table 2: Configuration files

3.2.2 Chipcon Library Files

Some of the functions in the library included with IAR Workbench cannot be used with CC2430.

The files which are described here are part of the Chipcon library and can be downloaded from www.chipcon.com.

In the IAR standard library, cexit will by default occupy one of the four hardware breakpoints. To free this breakpoint include the file below in the project.

- Chipcon_cexit.s51

To use banked code model the following files have to be included in the project, they will overwrite the files that are included by default in the IAR library.

- Chipcon_cstartup.s51
- Chipcon_banked_code_support.s51

Note:

Add \$TOOLKIT_DIR\$\SRC\LIB\ to Options -> Assembler -> Additional include directives.

4 CC1110/ CC2510 Linker File

There is one linker file for the CC2510 and one for CC1110.

4.1 XData RAM

The linker files set up 4k of XData RAM. The range from 0xFDAA – 0xFEFF is used to store register values during power mode (PM) 2 and 3. Hence, any data stored here before entering PM 2/3 will be lost. If PM 2/3 is not used, the entire range from 0xF000 – 0xFEFF can be used safely.

The XData RAM memory map in Figure 3 is reflected in the linker file.

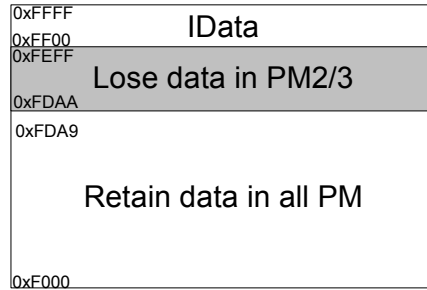


Figure 1: XData RAM Memory

Figure 3 shows how XData is organized. To place variables in the memory space which is not retained will have to be explicitly located in that memory segment (see chapter 7.1).

Note:

If your application is not using PM2/ PM3 you can change the linker file to use the full XData memory. Change the line below in `lnk51ew_cc1110.xcl` or `lnk51ew_cc2510.xcl`:

From: `-D_IXDATA_END=FDA9`

To: `-D_IXDATA_END=FEFF`

4.2 Code

The CCxx10 has 32 kB of code memory. This is reflected in the linker file the following way:

```
-D_CODE_START=0x0000
-D_CODE_END=0x7FFF // 32KB code
```

4.2.1 Create HEX-file

To generate a hex-file that can be downloaded to the CCxx10 by the Chipcon Flash Programmer, setup the Project Options as shown in Figure 7.

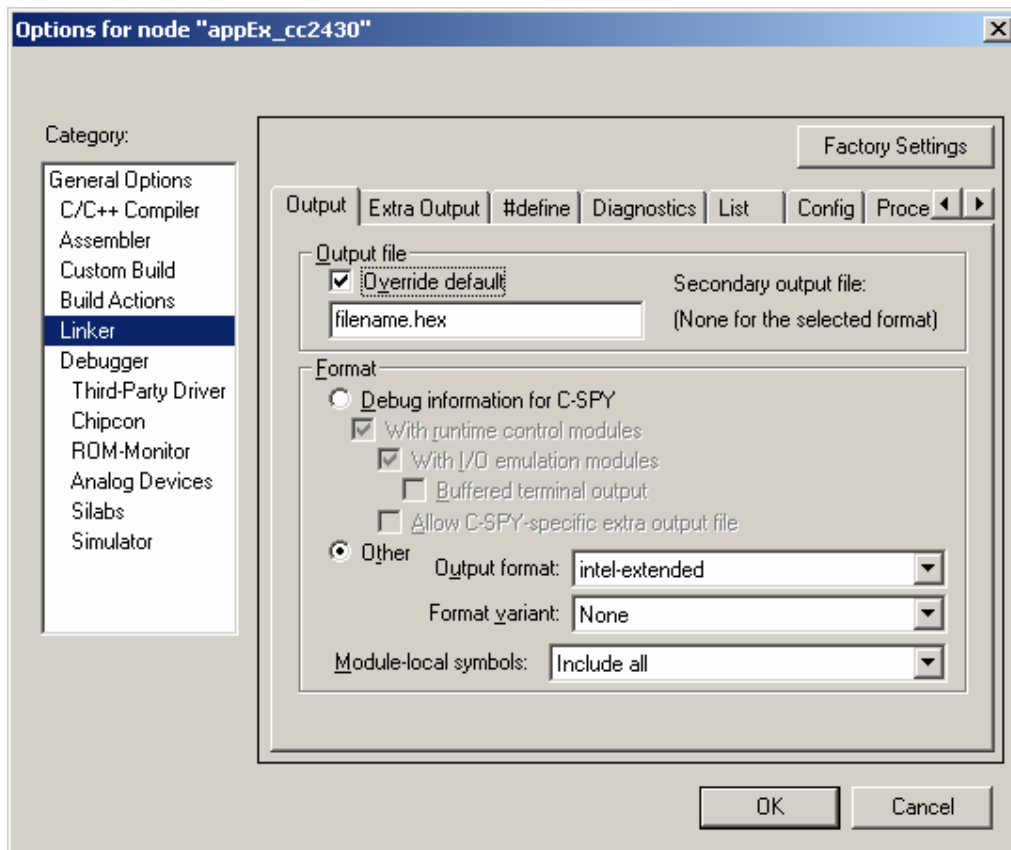


Figure 2: HEX-file generation

5 CC2430 Linker File

CC2430 is delivered in three different versions CC2430-F32, CC2430-F64 and CC2430-F128. There are two linker files for CC2430, `lnk51ew_cc2430.xcl` and `lnk51ew_cc2430b.xcl`. They both reflect the physical aspects of CC2430. `lnk51ew_cc2430b.xcl` is for CC2430-F128 and banked code model, `lnk51ew_cc2430.xcl` is for use with non-banked code, and can be edited to reflect any chip model.

5.1 XData RAM

The linker file is by default set up to use 4k of XData RAM.

The XData RAM memory map in Figure 3 is reflected in the linker file.

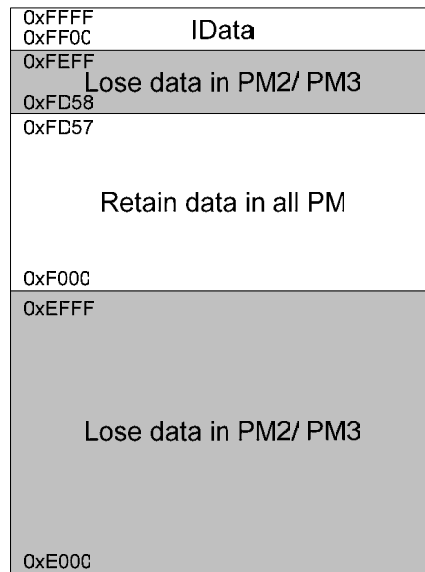


Figure 3: XData RAM Memory

CC2430 has 8k XData RAM memory, but only 4k is preserved during Power Mode 2 and Power Mode 3. Figure 3 shows how XData is organized. To place variables in the memory space which is not retained will have to be explicitly located in that memory segment (see chapter 7.1).

Note:

If your application is not using PM2/ PM3 you can change the linker file to use the full XData memory. Change the line below in `lnk51ew_cc2430[b].xcl`:

From: `-D_IXDATA_START=F000 // The internal xdata is 4k.`

To: `-D_IXDATA_START=E000 // using low power RAM as normal RAM`

5.2 Code

When using Near Code Model, a maximum of 64k (bank 0 and 1, Figure 4) of code memory is available (16 bits is used for address). When using Banked Code Model for CC2430-F128, 128k is available.

Lnk51ew_cc2430.xcl is set up to reflect CC2430-F128 and CC2430-F64 (both has 64 k flash for non-banked code). To reflect CC2430-F32, edit the file as described below as well as in the linker file. With use of this linker file, maximum code size is 64K.

Lnk51ew_cc2430.xcl contains this fragment:

```

-D_CODE_END=0xFFFF // Last address for code, CC2430-F64 and CC2430-F128
//-D_CODE_END=0x7FFF // Last address for code, CC2430-F32

-D_NEAR_CODE_END=0xFFFF // Last address for near code, CC2430-F64
// and CC2430-F128
//-D_NEAR_CODE_END=0x7FFF // Last address for near code, CC2430-F32
  
```

For use of CC2430-F32, interchange the lines that are commented out.



Figure 4: Code banking

5.2.1 *Near code model*

For unbanked code, the address space is continuous and straight forward to use, see Figure 5. The “Physical View” is showing the address space as it is observed physically in the CC2430-F64 and CC2430-F128. The “Linker View” is showing how the linker map addresses to physical address, and “Debugger view” is showing where in the “Disassembly Window” the code can be found.

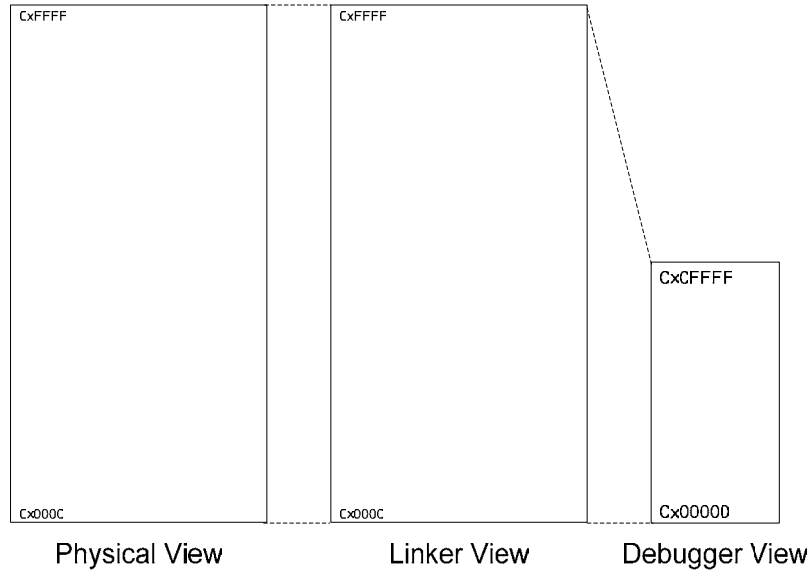


Figure 5: Near Code Memory

5.2.2 Banked code model

In Banked Code Model things get a bit trickier. Figure 6 shows the address space.

Note:
In "Linker View" the address space is not continuous.

To explicitly locate code in each bank, see chapter 7.1

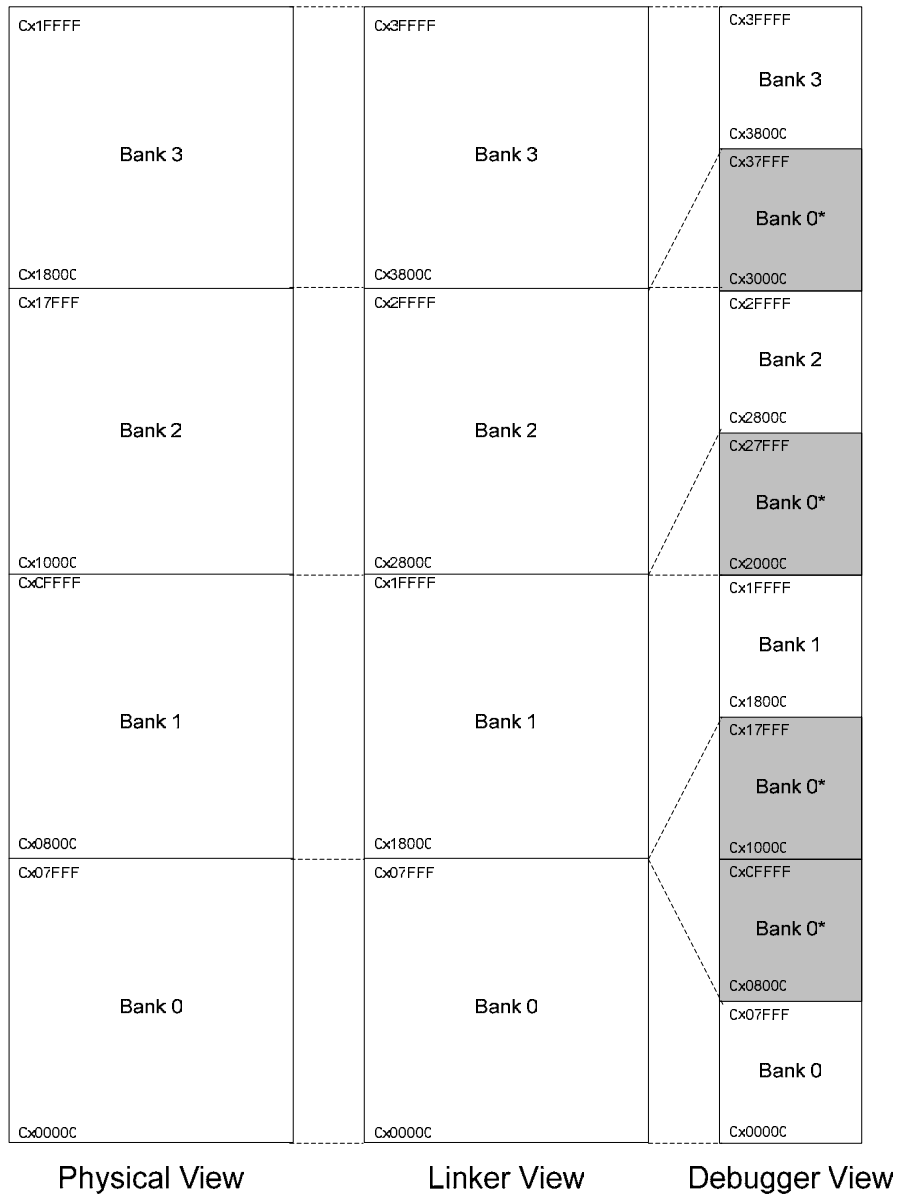


Figure 6: Banked Code Memory

"Debugger View" is upside-down in the IAR Disassembly Window in relation to Figure 6. "Bank 0*" in "Debugger View" is a copy of "Bank 0" and should not be taken into account.

5.2.3 Create HEX-file

Because of the non-continuous address space when using banked code model, the HEX file generated will not be usable with the Chipcon Flash Programmer. To map this address space into one continuous address range, include the line below into the xcl-file or insert it in the IAR IDE as shown in Figure 8. If this line is included the C-Spy debugger cannot be used.

```
-M(CODE)[(_CODEBANK_START+_FIRST_BANK_ADDR)-
(_CODEBANK_END+_FIRST_BANK_ADDR)]*_NR_OF_BANKS+10000=0x8000
```

To generate the file, setup the Project Options as shown in Figure 7.

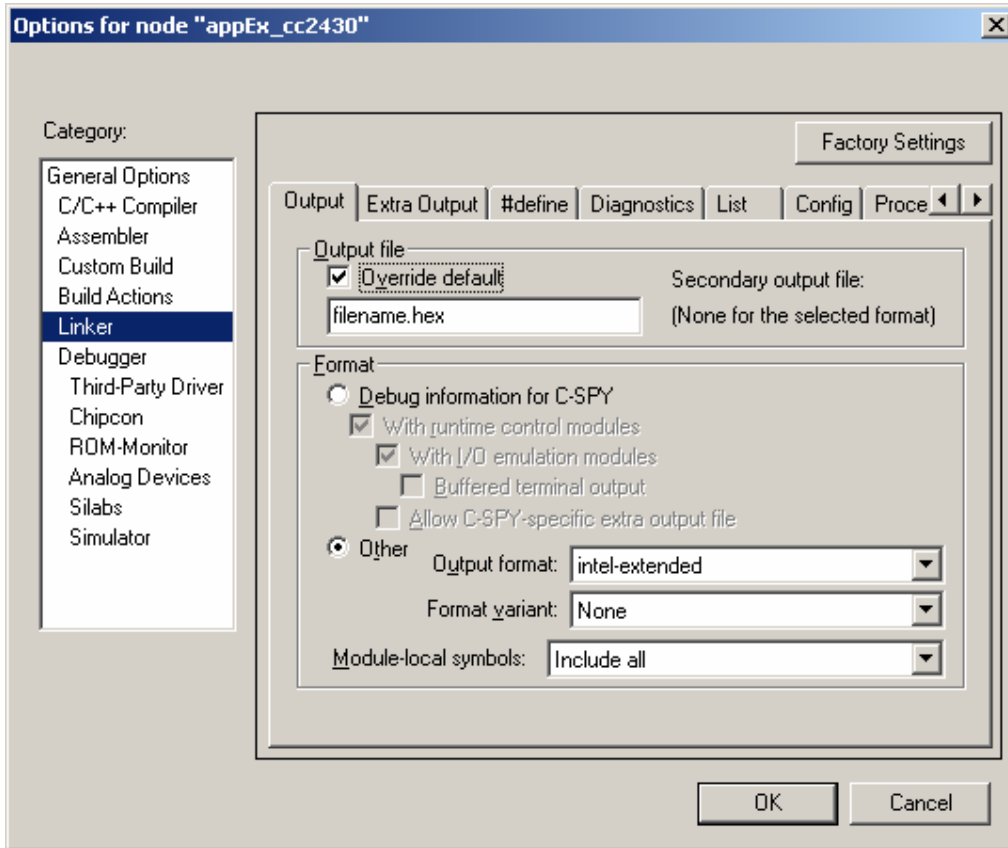


Figure 7: HEX-file generation

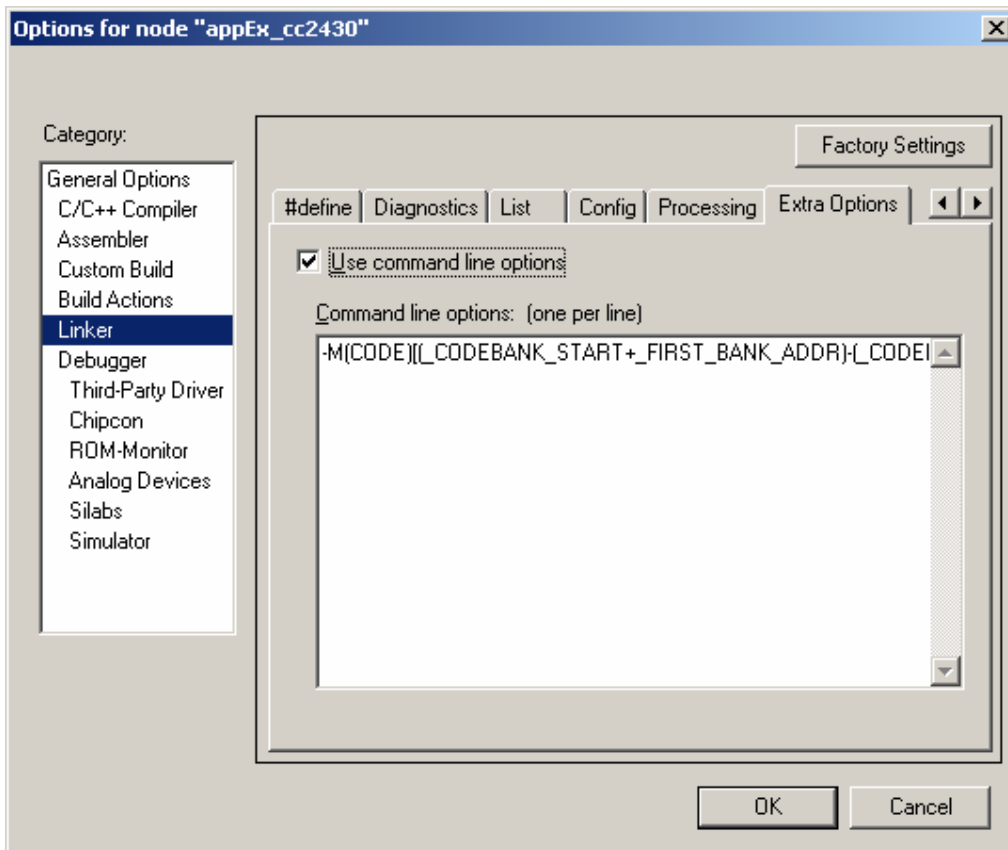


Figure 8: Address translation for Banked Code

6 Debugger

The debugger is configured to match the specific chip with use of a definition file. For CC2430 the configuration file is named CC2430.ddf. For the CCxx10 the file is named CCxx10.ddf (xx refers to either 11 or 25). To setup your project correctly, see chapter 9.

Some of the internal registers will disturb the state of the chip when they are read. These registers will consequently not be shown with correct values in the register view window, see Figure 9 . They will always be shown with value 0x00. (e.g. RFD, ADCH, ADCL, ENDO)

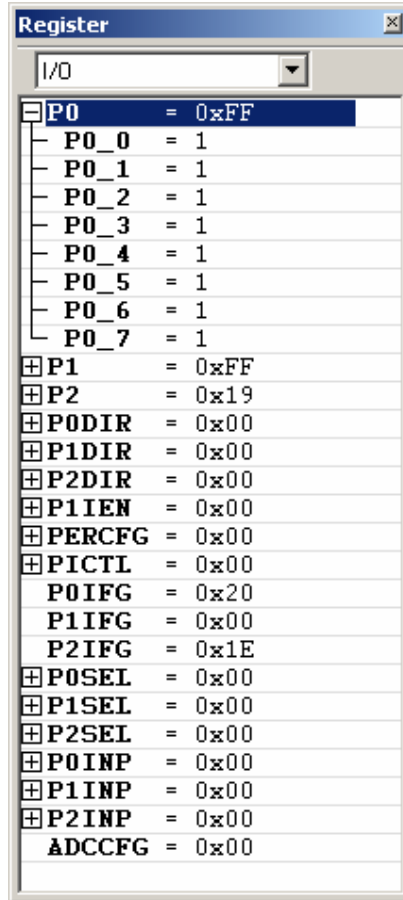


Figure 9: Register Window

7 Absolute Placement of Code and Variables

This chapter shows how to place code and variables at absolute addresses, and the chapter is mainly intended for the CC2430. For an extended description please refer to the IAR user manual.

7.1 Code

The linker file for CC2430-F128 has defined one code space for each bank. It is not required to use these definitions for banked code model. The linker will distribute the code automatically.

```
int f() @ "BANK1"{
    return 1;
}

#pragma location="BANK1"
int g(){
    return 2;
}

__near_func int main( void )
{
    int a = g();
    int b = f();
    return 0;
}
```

Both f() and g() will be placed in code segment named BANK1. The main routine will be placed in BANK 1 by default. To place main (or some other routines) in bank 0 use the keyword `__near_func`, as indicated in the listing above.

The linker file for CC2430-F128 defines "BANK1", "BANK2" and "BANK3".

Note:

There is no banking for the CCxx10, as they only have 32 kB code memory size.

7.2 Variables

Absolute placement of variables is described below.

```
__no_init int myArray[128] @ "PM0_XDATA";
__no_init int myInteger @ 0xE000;
```

"PM0_XDATA" is defined in the linker file. This is the address space from 0xE000 to 0xEFFF. It is necessary to explicitly define variables to be located in this area; if variables are "placed by default" they will be located in address range 0xF000 to 0xFD57.

8 CC2430 IEEE address

When delivered in a kit each CC2430 has an IEEE address stored in code memory. The segment is defined to be the last eight byte on the last flash page. Table 3 gives the address.

Chip	Code model	Physical Address	IAR Linker Address
CC2430-F32	Near	0x07FF8	0x07FF8
CC2430-F64	Near	0x0FFF8	0x0FFF8
CC2430-F128 ¹	Near	0x0FFF8	0x0FFF8
CC2430-F128	Banked	0x1FFF8	0x3FFF8

Table 3: IEEE address space

The linker file defines a segment for the IEEE address, named "IEEE_ADDRESS_SPACE".

8.1 Write an address

Use Chipcon Flash Programmer, available from www.chipcon.com, to write an IEEE address to CC2430 or see the next section. Information about Chipcon Flash Programmer is available in Chipcon Flash Programmer User Manual.

It is possible to write the IEEE address as part of a C program. "IEEE_ADDRESS_SPACE" is defined in the linker file. To write an address to this segment, include the code below in the C program (change the address). The IEEE address which the chip was delivered with is written on the development card.

```
__root__code const unsigned char IEEE_ADDRESS[8] @ "IEEE_ADDRESS_SPACE" =
{0x00, 0x01, 0x02, 0x03, 0x04, 0x05, 0x06, 0x07};
```

If the chip already contains an address, this address will be overwritten by inclusion of this example code.

8.2 Read an address

If the IEEE address is written to code as the example code in chapter 8.1 shows, it can easily be read with use of the same variable.

If the address is stored in the chip, it can be read with use of the example code shown below. If interrupt is enabled, remember to turn this off before calling the routine.

If the project is using code model near, set flash size to 64 for both CC2430-F64 and CC2430-F128.

¹ Not programmed when delivered


```
// #define CC2430_FLASH_SIZE 32
#define CC2430_FLASH_SIZE 64
// #define CC2430_FLASH_SIZE 128

#if (CC2430_FLASH_SIZE == 32)
    #define IEEE_ADDRESS_ARRAY 0x7FF8
#elif (CC2430_FLASH_SIZE == 64) || (CC2430_FLASH_SIZE == 128)
    #define IEEE_ADDRESS_ARRAY 0xFFFF8
#endif

__near_func void getIEEEAddress(unsigned char *a){
#if ( CC2430_FLASH_SIZE == 128 )
    unsigned char bank;
    bank = MEMCTR;
    // switch to bank 3
    MEMCTR |= 0x30;
#endif
    a[0] = *(unsigned char __code *)(IEEE_ADDRESS_ARRAY + 0);
    a[1] = *(unsigned char __code *)(IEEE_ADDRESS_ARRAY + 1);
    a[2] = *(unsigned char __code *)(IEEE_ADDRESS_ARRAY + 2);
    a[3] = *(unsigned char __code *)(IEEE_ADDRESS_ARRAY + 3);
    a[4] = *(unsigned char __code *)(IEEE_ADDRESS_ARRAY + 4);
    a[5] = *(unsigned char __code *)(IEEE_ADDRESS_ARRAY + 5);
    a[6] = *(unsigned char __code *)(IEEE_ADDRESS_ARRAY + 6);
    a[7] = *(unsigned char __code *)(IEEE_ADDRESS_ARRAY + 7);
#if ( CC2430_FLASH_SIZE == 128 )
    // restore old bank settings
    MEMCTR = bank;
#endif
}

unsigned char addr[8];

int main( void )
{
    getIEEEAddress(addr);
    for(;;);
}
```

9 Tutorial

This chapter shows how to set up a new project for CC2430 in the IAR Workbench. A project for CCxx10 can be set up in a similar fashion by replacing the CC2430-specific files with the corresponding files for the chip in question.

The setup which is shown here use settings used for common projects. Both setup for project using near code model and banked code model is presented.

The tutorial shows only screen shots from settings which need to be changed.

9.1 Create a new project

To quickly create a CC2430 application Chipcon recommends that the user begins by creating a software project.

From the “Project” menu, choose “Create New Project...”.

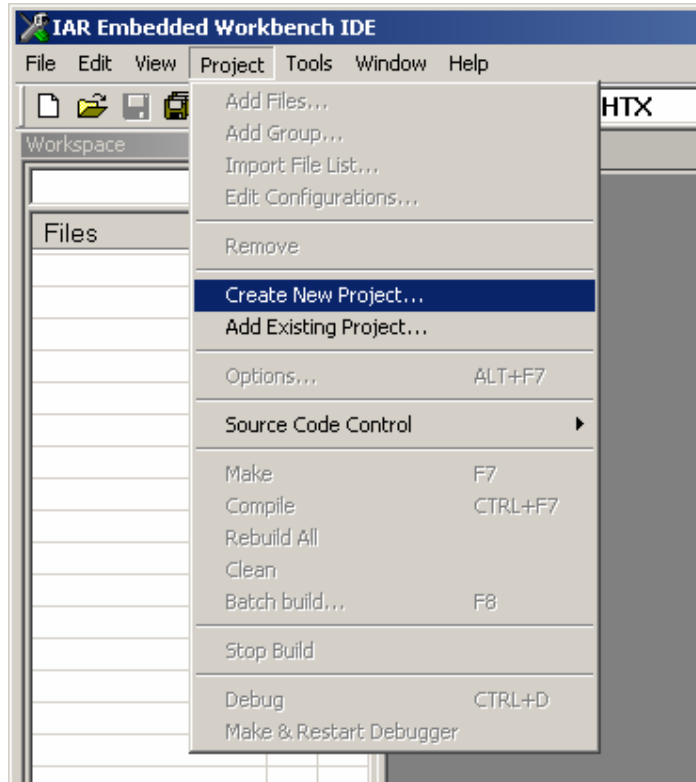


Figure 10: Create New Project

Choose “Empty project” and press OK.

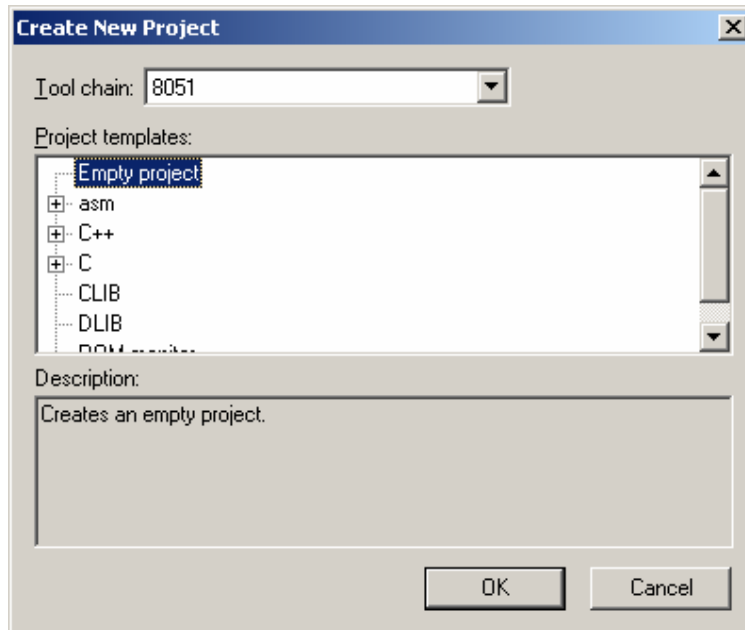


Figure 11: Choose Project Type

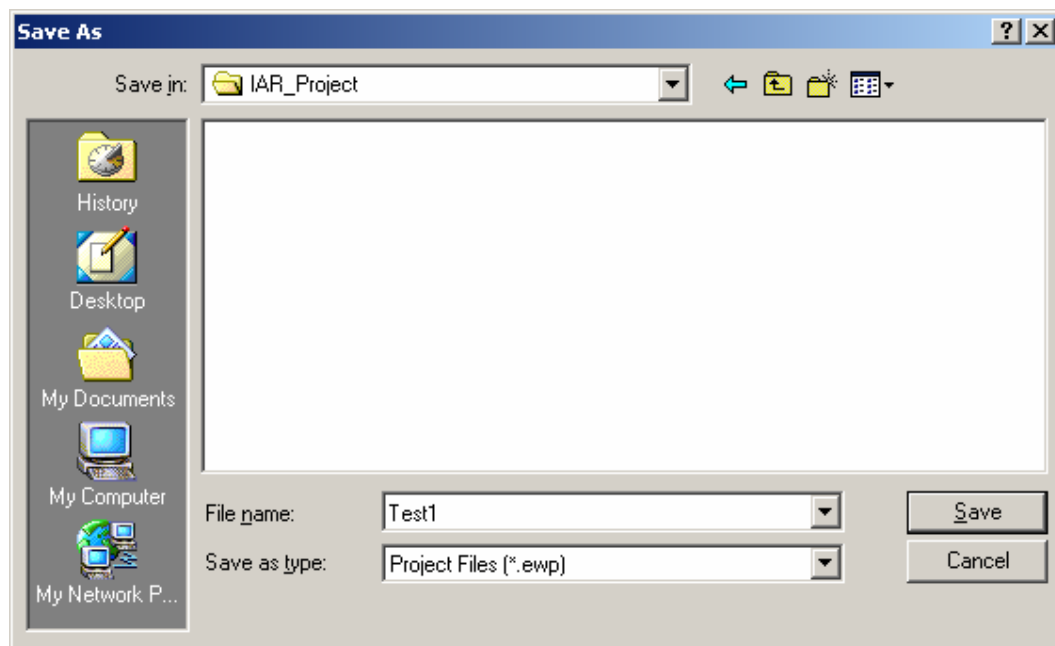


Figure 12: Save Project

Give the new project a name and press "Save".

9.2 Options

To set up the project for use with CC2430 choose "Options" from the "Project" menu.

Chapter 9.2.1 describes all settings that need to be changed for CC2430 for code model near. This also applies to CCxx10. Chapter 9.2.2 describes the settings that differ from code model near to code model banked. This does not apply to CCxx10.

9.2.1 *General Options, Code Model Near (Applies also to CCxx10)*

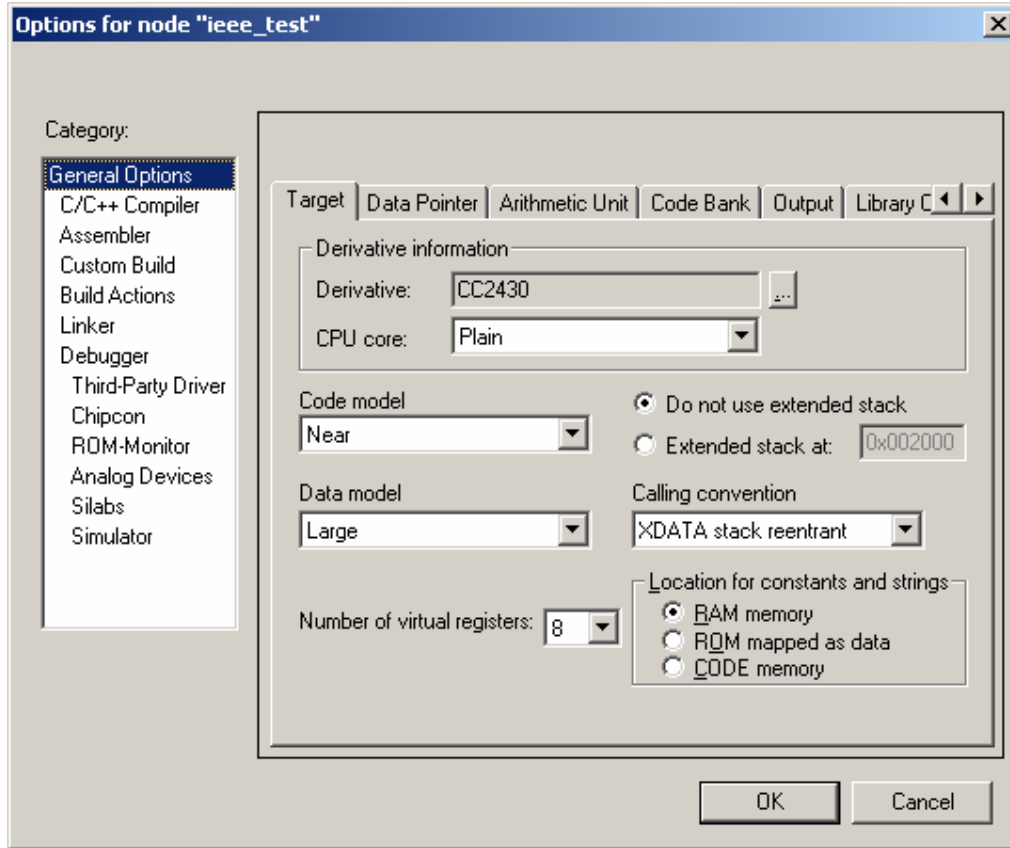


Figure 13: Target, Code Model Near

In the “Derivative information” box select the CC2430.i51 file located in folder: Embedded Workbench 4.05 \8051\config\derivatives\Chipcon.

Use  to select the file.

Set up rest of the settings on the “Target” settings as Figure 13 shows.

Use one data pointer. It's important to set "DPTR select" to "Set using XOR/ AND" even if only one DPTR is in use.

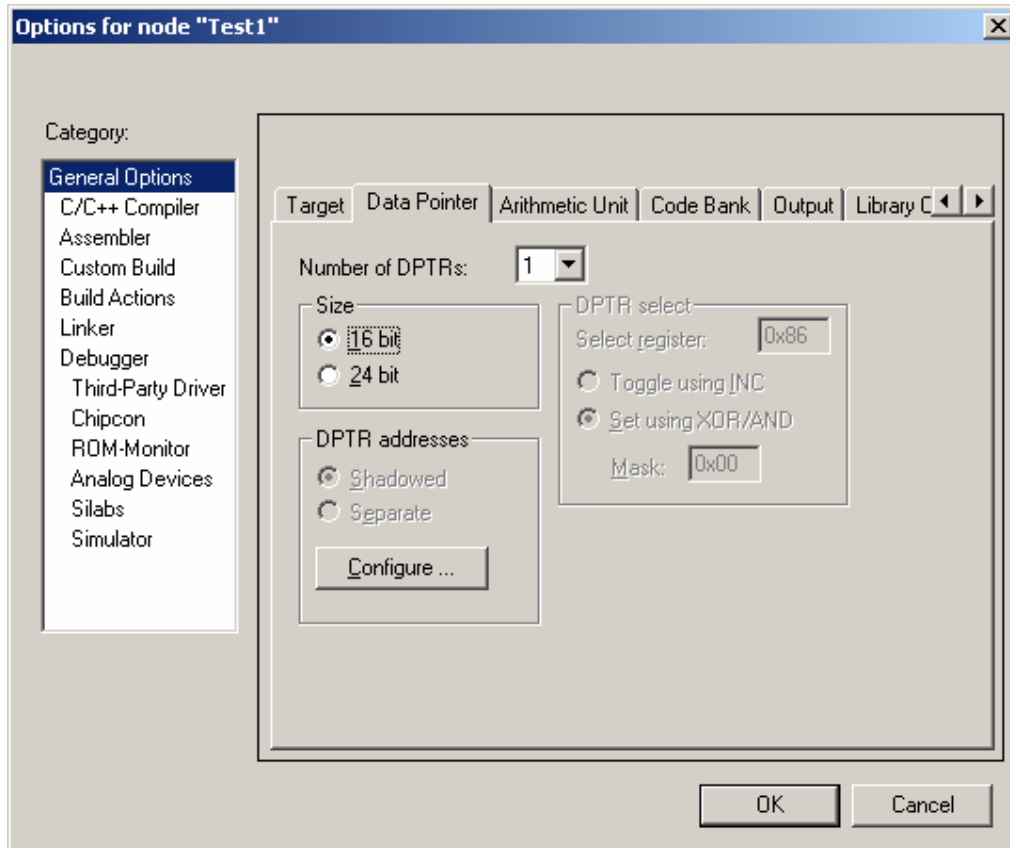


Figure 14: Data Pointer

Change XDATA stack size to 0x1FF.

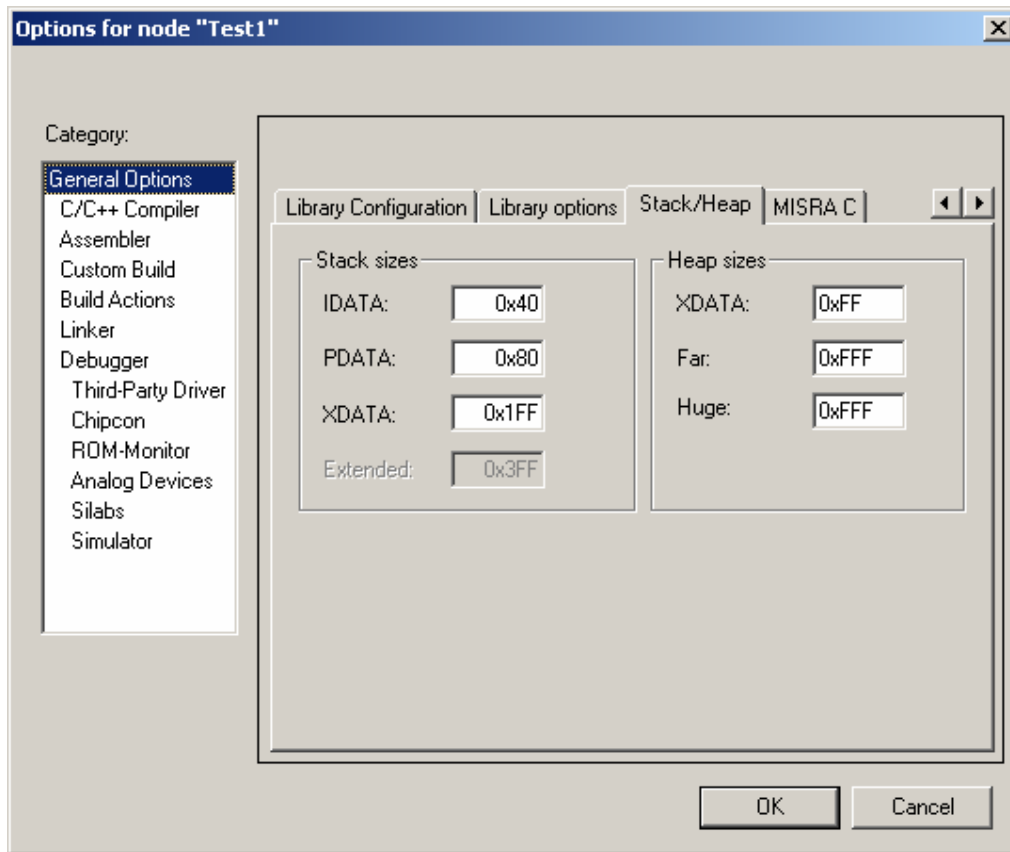


Figure 15: Stack/ Heap settings

9.2.2 General Options, Code Model Banked (Does not apply to CCxx10)

Note:
Remember to include Chipcon_cstartup.s51 and Chipcon_banked_code_support.s51 (chapter 3.2.2 when using code model banked).

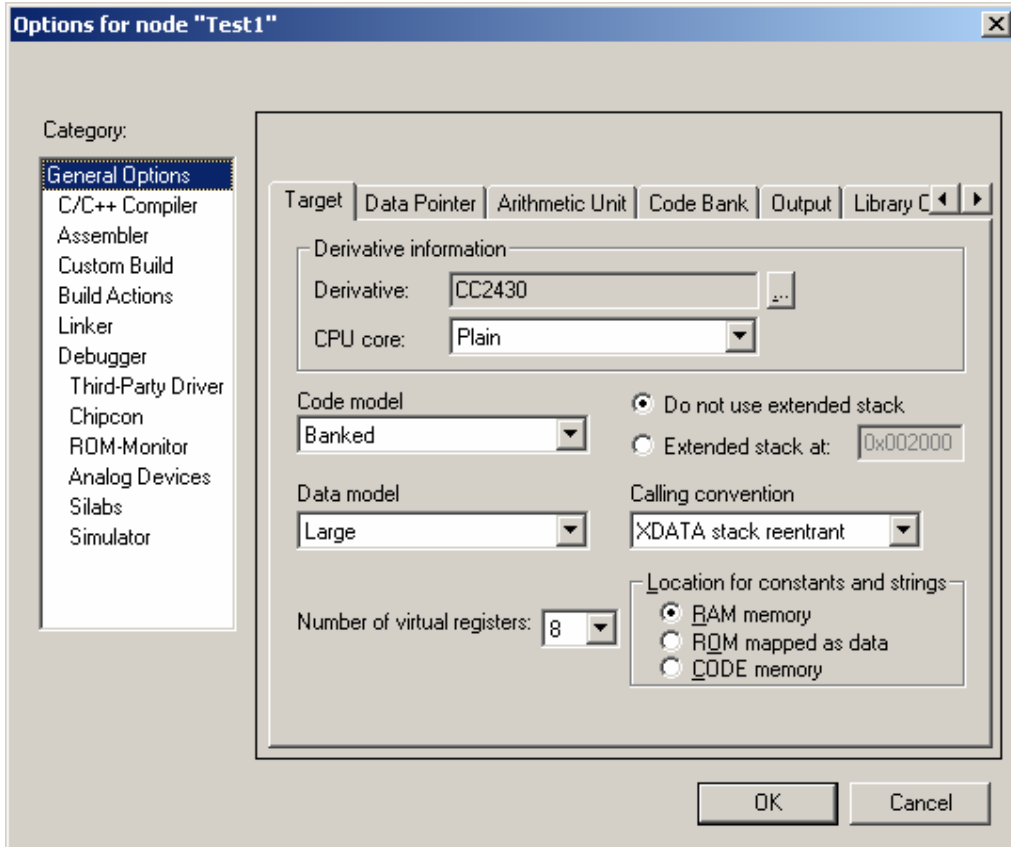


Figure 16: Target, Code Model Banked

The settings in Figure 17 are only available when Code Model Banked is active

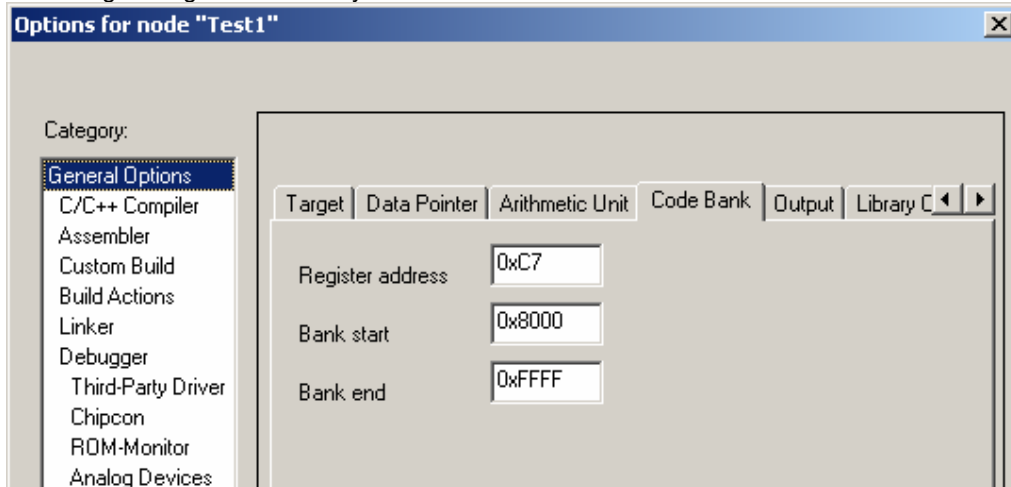


Figure 17: Code Bank

9.2.3 Linker

Choose correct linker file, see chapter 4, as "Linker command file".

Code Model	File
Near	lnk51ew_cc2430.xcl
Banked	lnk51ew_cc2430b.xcl

Table 4: Linker files

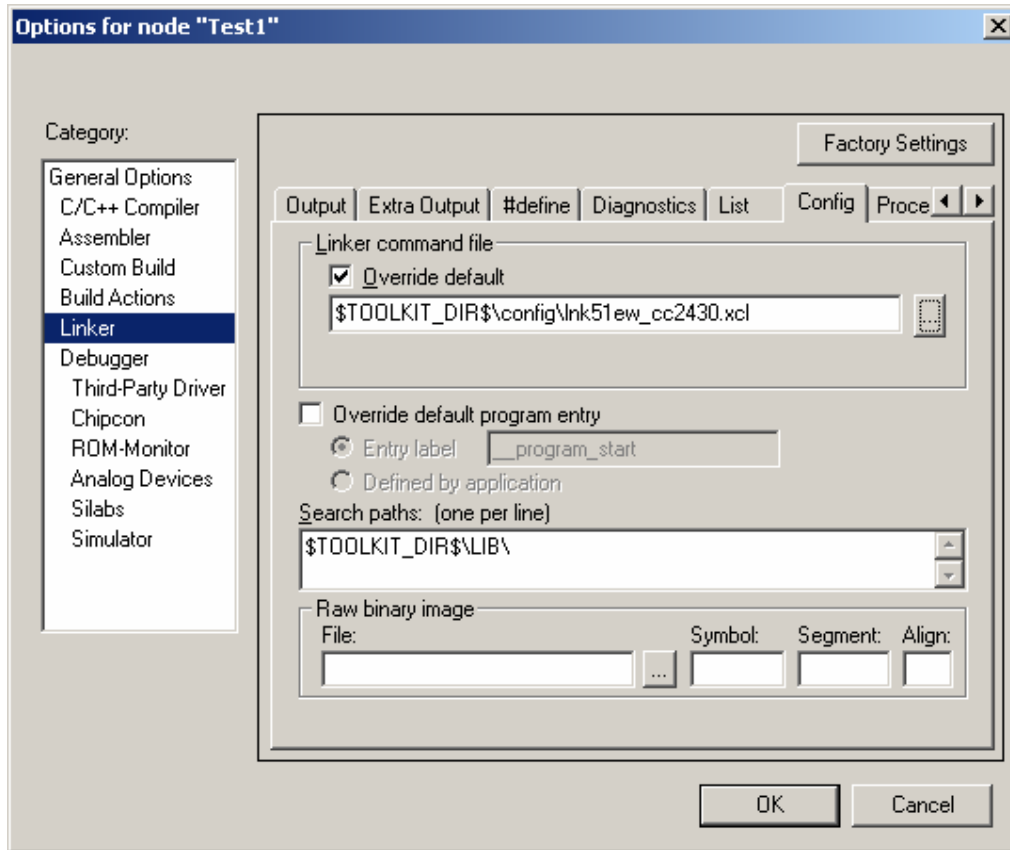


Figure 18: Linker

9.2.4 Debugger

Use “Chipcon” as debugger, and check that the “Device Description file” is set to CC2430.ddf. The ddf file is located in: Embedded Workbench 4.05 \8051\config\derivatives\Chipcon.

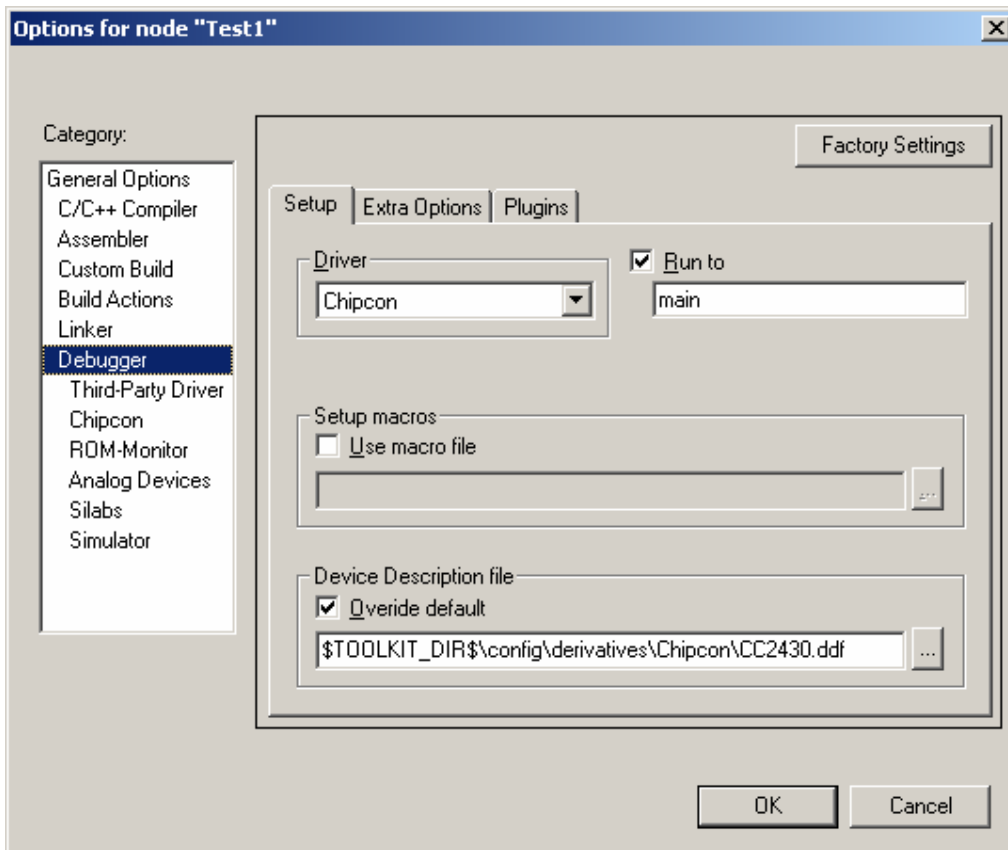


Figure 19: Debugger

9.3 Include source files

To create a new source file choose File -> New -> File.

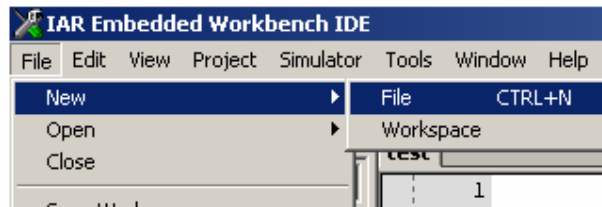


Figure 20: Create new source file

Edit the file and save it into your project directory.

To add this, or another file to your project, choose Project -> Add files... Locate correct file and click "Open".

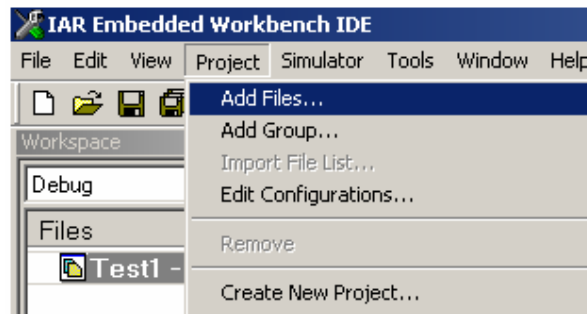


Figure 21: Add files to project

9.4 Compile and Link

To compile and link your project choose "Make" from the "Project" menu, or press F7.

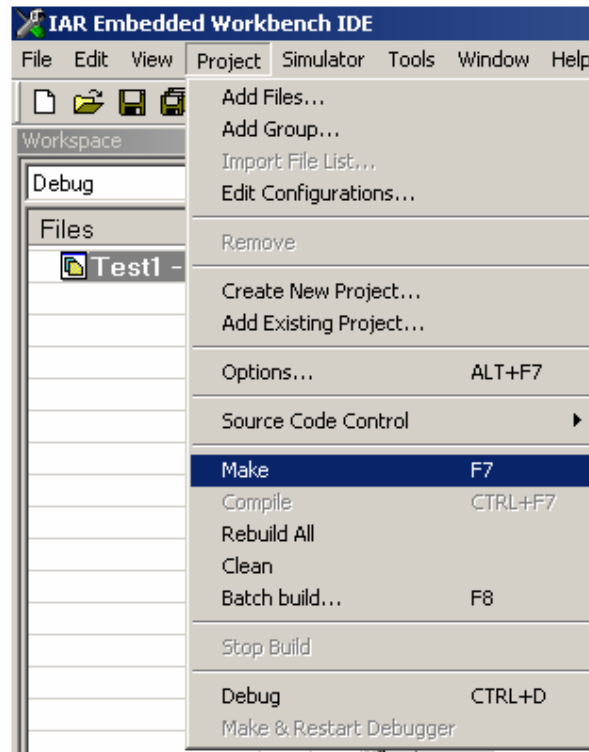


Figure 22: Compile and Link

9.5 Debug

Start the debugger with “Debug” from the “Project” menu, or press CTRL+D.

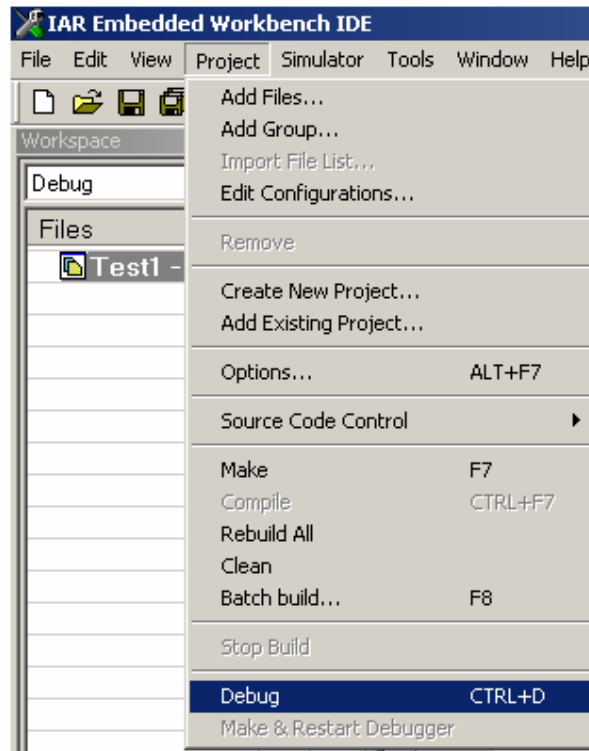


Figure 23: Start debugger

Use of the debugger is described in the IAR user manual.

10 Document history

Revision	Date	Description/Changes
1.2	2006-02-16	Added CC2510 and CC1110. Changed layout.
1.1	2006-01-18	Removed link to configuration files on web
1.0	2005-12-15	Initial release.

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